SM843256

10 Gigabit Ethernet and SONET, 6 output, Ultra-Low Jitter LVPECL Frequency Synthesizer

General Description

The SM843256 provides a low-noise timing solution for high speed, high accuracy synthesis of clock signals. Common applications include SONET, Gigabit Ethernet, 10 Gigabit Ethernet, and similar networking standards. It includes a unique power reduction methodology, along with a patented RotaryWave™ architecture that provides a very stable clock with very low noise.

Power supplies of either 3.3V or 2.5V are supported, with superior jitter and phase noise performance. The device synthesizes different low noise LVPECL output frequencies such as 125MHz, 156.25MHz, 312.5MHz, and 625MHz for Ethernet applications; 77.76MHz, 155.52MHz, 311.04MHz, and 622.08MHz for SONET applications. The crystal reference frequencies used include 25MHz and 19.44Mhz for Ethernet and SONET applications, respectively.

The SM843256 is an excellent replacement for IDT Femto-clocks, with improved accuracy, power consumption, waveform integrity, and jitter.

Data sheets and support documentation can be found on Micrel's web site at: www.micrel.com.

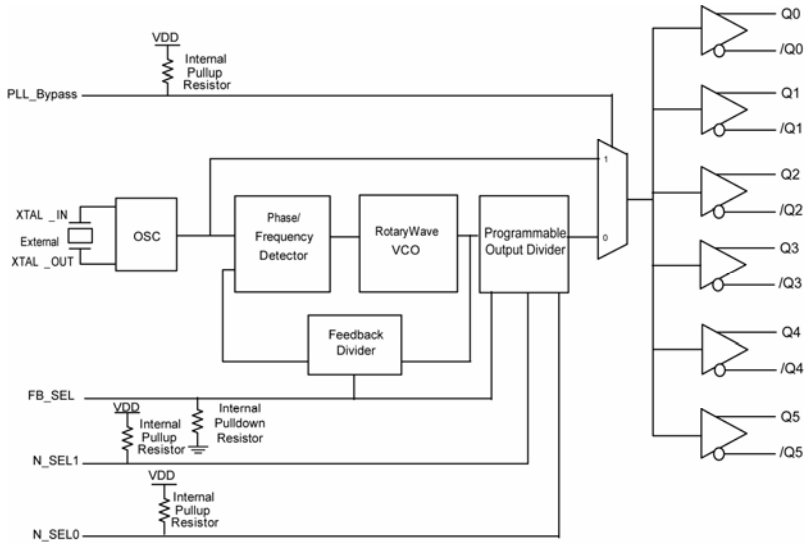
Features

- Generates six LVPECL outputs
- 2.5V or 3.3V operating range
- Typical phase jitter @ 156.25MHz (1.875MHz to 20MHz): 80fs (typical) @ 3.3V
- 75MHz to 625MHz output frequencies
- Industrial temperature range
- Green, RoHS, and PFOS compliant
- Available in 24-pin TSSOP EPAD
- Operating supply modes:
  Core/Output
  3.3V/3.3V, 3.3V/2.5V, 2.5V/2.5V

Applications

- SONET
- Gigabit Ethernet
- 10-Gigabit Ethernet
- Infiniband

Block Diagram



RotaryWave is a trademark of Multigig, Inc.

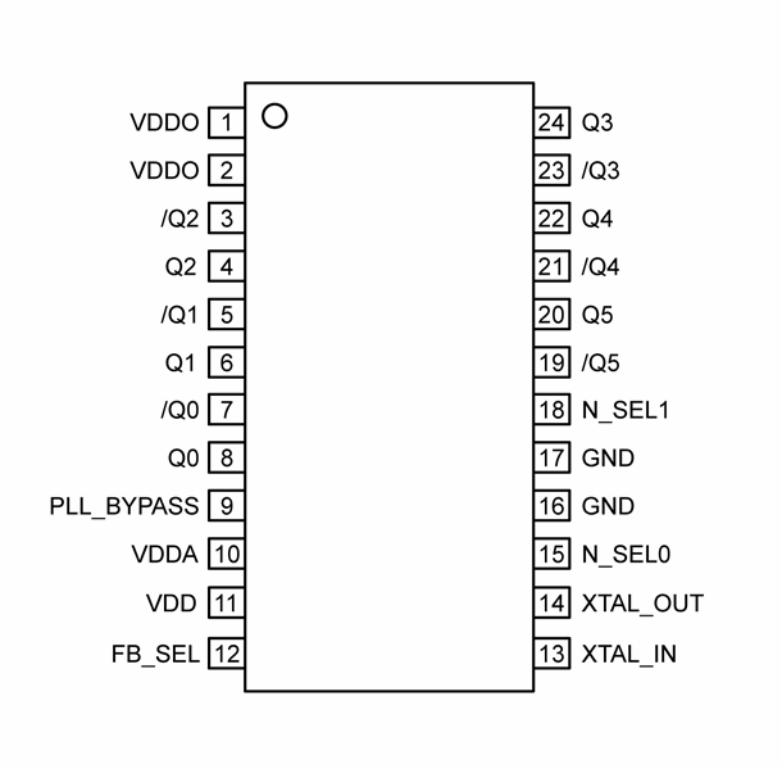
Ordering Information[1, 2]

Part Number	Marking	Shipping	Junction Temperature Range	Package
SM843256KA	843256	Tube, Tape & Reel	–40° to +85°C	24-Pin TSSOP EPAD

Notes:

1. Devices are Green, RoHS, and PFOS Compliant.
2. Lead finish is 100% matte tin.

Pin Configuration



24-Pin TSSOP EPAD
(Top View)

Pin Description

Pin Number	Pin Name	Pin Type	Pin Level	Pin Function
1, 2	V_{DDO}	PWR		2.5V or 3.3V Power Supply
3, 4	/Q2, Q2	O, (DIF)	LVPECL	Differential Clock Output
5, 6	/Q1, Q1	O, (DIF)	LVPECL	Differential Clock Output
7, 8	/Q0, Q0	O, (DIF)	LVPECL	Differential Clock Output
9	PLL_BYPASS	I, (SE)	LVCMOS	Pull-Up 45k, Single-Ended Input Select Pin. Logic (0) = PLL Output Logic (1) = Xtal Reference
10	V_{DDA}	PWR		Analog 3.3V or 2.5V Power Supply
11	V_{DD}	PWR		3.3V or 2.5V Power Supply
12	FB_SEL	I, (SE)	LVCMOS	Pull-Down 45k, Single-Ended Input Select Pin
13	XTAL_IN	I, (SE)	12pF crystal	Crystal Reference Input, no load caps needed.
14	XTAL_OUT	O, (SE)	12pF crystal	Crystal Reference Output, no load caps needed.
15	N_SEL0	I, (SE)	LVCMOS	Pull-Up 45k, Single-Ended Input Select Pin
16, 17	GND	PWR		Ground
18	N_SEL1	I, (SE)	LVCMOS	Pull-Up 45k, Single-Ended Input Select Pin
19, 20	/Q5, Q5	O, (DIF)	LVPECL	Differential Clock Output
21, 22	/Q4, Q4	O, (DIF)	LVPECL	Differential Clock Output
23, 24	/Q3, Q3	O, (DIF)	LVPECL	Differential Clock Output

Input and Output Frequency Table

XTAL (MHz)	FB_SEL	N_SEL1	N_SEL0	Outputs (MHz)	Application
24	0	0	0	600	-
24	0	0	1	300	-
24	0	1	0	150	SAS/SATA
24	0	1	1	120	-
25	0	0	0	625	10 Gigabit Ethernet
25	0	0	1	312.50	10 Gigabit Ethernet
25	0	1	0	156.25	10 Gigabit Ethernet
25	0	1	1	125	Gigabit Ethernet/Infiniband/PCI/PCI-E/PCI-X
18.75	1	0	0	600	-
18.75	1	0	1	300	-
18.75	1	1	0	150	SAS/SATA
18.75	1	1	1	75	SAS/SATA
19.44	1	0	0	622.08	10 Gigabit Ethernet/SONET
19.44	1	0	1	311.04	SONET
19.44	1	1	0	155.52	SONET
19.44	1	1	1	77.76	SONET
19.53125	1	0	0	625	10 Gigabit Ethernet
19.53125	1	0	1	312.5	10 Gigabit Ethernet
19.53125	1	1	0	156.25	10 Gigabit Ethernet
19.53125	1	1	1	78.125	10 Gigabit Ethernet

Absolute Maximum Ratings[1]

Supply Voltage (V_{DDA}, V_{DD}, V_{DDO}).....+4.6V
Input Voltage (V_{IN}).....-0.50V to V_{DD}+0.5V
LVPECL Output Current (I_{OUT})
Continuous.....50mA
Surge.....100mA
Lead Temperature (soldering, 20sec.).....260°C
Case Temperature .....115°C
Storage Temperature (T_s) .....-65°C to +150°C

Operating Ratings[2]

Supply Voltage (V_{DDO})..... +2.375V to +3.465V
Supply Voltage ($V_{DD,}$ V_{DDA})..... +2.375V to +3.465V
Ambient Temperature (T_A)..... –40°C to +85°C
Junction Thermal Resistance[3]
TSSOP (θ_{JA})(Still Air).....32°C/W

DC Electrical Characteristics[4]

V_{DDA} = V_{DD} = 3.3V ±5% or 2.5V ±5%, V_{DDO} = 2.5V ±5%, T_A = –40°C to +85°C, unless noted.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{DDO}	2.5V Operating Voltage		2.375	2.5	2.625	V
V_{DDA},V_{DD}	3.3V Operating Voltage		2.375	3.3	3.465	V
I_{DDA}	Analog Supply Range	F_{OUT} = 156.25MHz		55	65	mA
		F_{OUT} = 625.00MHz		56		
I_{DD}	Core Supply Current	F_{OUT} = 156.25MHz		13	17	mA
		F_{OUT} = 625.00MHz		13		
I_{DDO}	I/O Supply Range	F_{OUT} = 156.25MHz		235	TBD	mA
		F_{OUT} = 625.00MHz		330		

V_{DDA} = V_{DD} = V_{DDO} = 3.3V ±5%, T_A = –40°C to +85°C, unless noted.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{DDA}, V_{DD}, V_{DDO}	3.3V Operating Voltage		3.135	3.3	3.465	V
I_{DDA}	Analog Supply Range	F_{OUT} = 156.25MHz		55	65	mA
		F_{OUT} = 625.00MHz		56		
I_{DD}	Core Supply Current	F_{OUT} = 156.25MHz		13	17	mA
		F_{OUT} = 625.00MHz		13		
I_{DDO}	I/O Supply Range	F_{OUT} = 156.25MHz		256	282	mA
		F_{OUT} = 625.00MHz		366		

Notes:

1. Permanent device damage may occur if absolute maximum ratings are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.
2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.
3. Package thermal resistance assumes exposed pad is soldered (or equivalent) to the devices most negative potential on the PCB.
4. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

LVPECL DC Electrical Characteristics[5, 6]

V_{DDA} = V_{DD} = 3.3V ±5% or 2.5V ±5%, V_{DDO} = 2.5V or 3.3V ±5%, T_A = –40°C to +85°C, unless noted.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{OH}	Output High Voltage	50Ω to V_{DDO}-2V	V_{DDO} –1.145	V_{DDO} –0.97	V_{DDO} –0.845	V
V_{OL}	Output Low Voltage	50Ω to V_{DDO}-2V	V_{DDO} –1.945	V_{DDO} –1.77	V_{DDO} –1.645	V
V_{SWING}	Peak-to-Peak Output Voltage Swing	Figure 1	0.6	0.8	1.0	V

LVCMOS DC Electrical Characteristics[6]

V_{DDA} = V_{DD} = 3.3V ±5% or 2.5V ±5%, V_{DDO} = 2.5V or 3.3V ±5%, T_A = –40°C to +85°C, unless noted.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{IH}	Input High Voltage		2		V_{DD} +0.3	V
V_{IL}	Input Low Voltage		-0.3		0.8	V
I_{IH}	Input High Current (FB_SEL)	V_{DD} = V_{IN} = 3.465V			150	µA
I_{IH}	Input High Current (PLL_BYPASS), (N_SEL0), (NSEL1)	V_{DD} = V_{IN} = 3.465V			5	µA
I_{IL}	Input Low Current (FB_SEL)	V_{DD} = 3.465V, V_{IN} = 0V	-5			µA
I_{IL}	Input Low Current (PLL_BYPASS), (N_SEL0), (NSEL1)	V_{DD} = 3.465V, V_{IN} = 0V	-150			µA

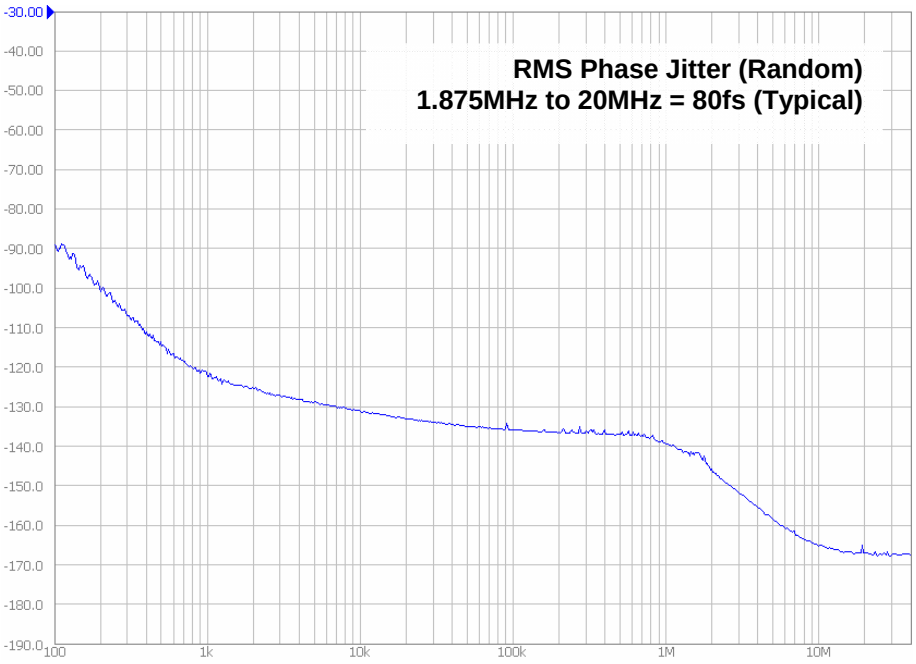
AC Electrical Characteristics[7]

V_{DDA} = V_{DD} = 3.3V ±5% or 2.5V ±5%, V_{DDO} = 2.5V or 3.3V ±5%, T_A = –40°C to +85°C, unless noted.

Symbol	Parameter	Condition	Min	Typ	Max	Units
F_{OUT}	Output Frequency	Refer to Frequency Table	75		625	MHz
T_R/T_F	LVPECL Output Rise/Fall Time	20% – 80%	100	175	350	ps
ODC	Output Duty Cycle		46	50	54	%
T_{SKEW}	Output-to-Output Skew	Note 8			45	ps
T_{LOCK}	PLL Lock Time				20	ms
T_{jit}(∅)	RMS Phase Jitter (Output = 156.25 MHz)	Integration Range (12kHz – 20MHz)		251		fs
		Integration Range (1.875MHz – 20MHz)		80		fs

Notes:

5. See Figure 4 for load test circuit example.
6. The circuit is designed to meet the DC specifications shown in the above table(s) after thermal equilibrium has been established.
7. The circuit is designed to meet the AC specifications shown in the above table(s) after thermal equilibrium has been established.
8. Defined as skew between outputs at the same supply voltage and with equal load conditions; Measured at the output differential crossing points.



Phase Noise Plot: 156.25MHz @ 3.3V

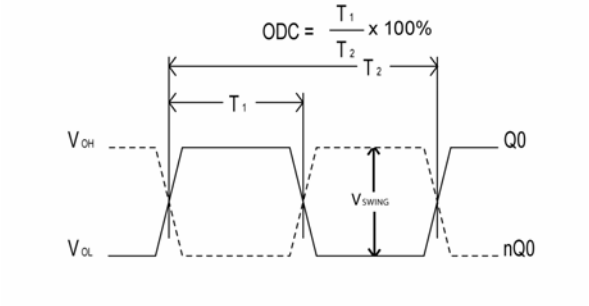


Figure 1. Duty Cycle Timing

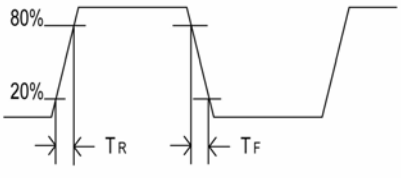


Figure 2. All Outputs Rise/Fall Time

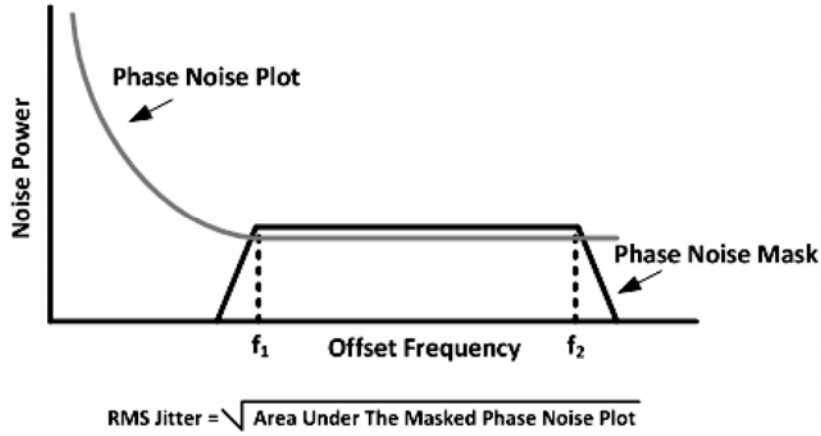


Figure 3. RMS Phase Noise/Jitter

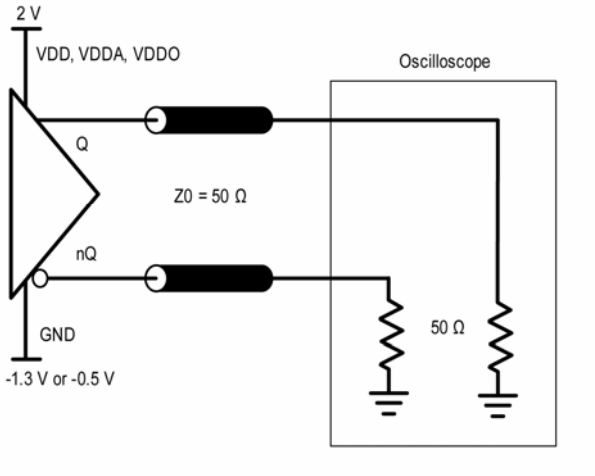


Figure 4. LVPECL Output Load and Test Circuit

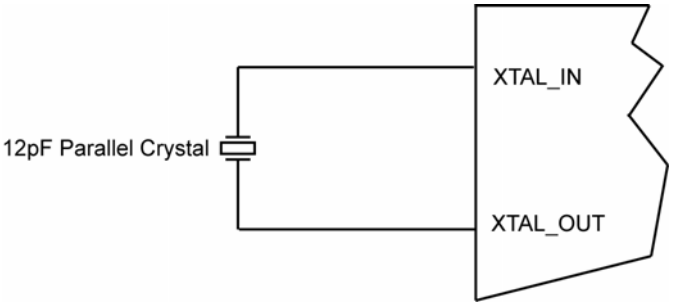
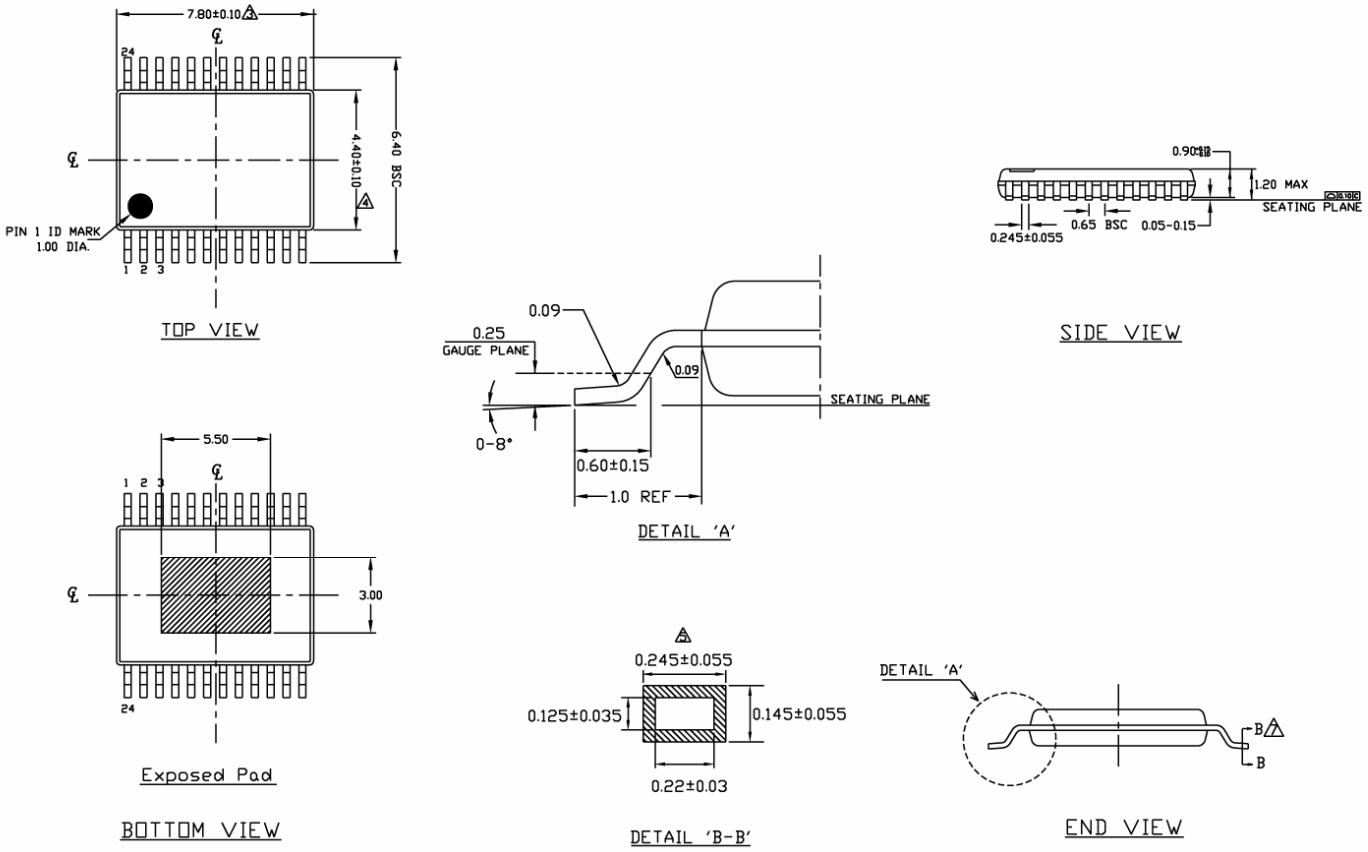


Figure 5. Crystal Input Interface

Package Information



NOTES:

1. DIMENSIONS ARE IN MM.
2. DIMENAIONS AND TOLERANCES PER ANSI Y14.5M-1994.
3. DIMENSION 'D' DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURR.
4. DIMENSION 'E1' DOES NOT INCLUDE INTERNAL FLASH OR PROTRUSION.
5. DIMENSION 'b' DOES NOT INCLUDE DAMBAR PROTRUSION.
6. "N" IS THE MAXIMUM NUMBER OF LEAD TERMINAL POSITIONS FOR THE SPECIFIED PACKAGE LENGTH.
7. CROSS SECTION B-B TO BE DETERMINED AT0.10 TO 0.25mm FROM THE LEAD TIP

24-pin EPAD TSSOP

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